

SEMI-e2025 The 7th Shenzhen International Semiconductor Exhibition

SEPT. 10-12, 2025

Shenzhen World Exhibition & Convention Center (Bao'an New Site)







60,000 m²

Number of Exhibitors

900+

Number of Visitors

70,000

Number of Theme Activities

50⁺

Jiangsu Semiconductor Industry Association Shenzhen Semiconductor Industry Association Dongguan Integrated Circuit Industry Association

Organizer:

Shenzhen Zhongxincai Exhibition Co., Ltd.

Zhejiang Semiconductor Industry Association Chengdu Integrated Circuit Industry Association Shenzhen Zhongxincai Exhibition Co., Ltd.



Exhibition Introduction

SEMI-e 2025 The 7th Shenzhen International Semiconductor Exhibition will be held at Shenzhen World Exhibition & Convention Center (Bao'an New Site) on September 10-12, 2025! This exhibition will focus on various sub-sectors of the semiconductor industry, comprehensively showcasing new technologies, products, highlights and trends in the semiconductor industry. It will gather over 900 exhibitors, focusing on artificial intelligence, computing power storage, chip design, wafer manufacturing, advanced packaging, specialized equipment and components for semiconductors, advanced materials and carbon materials, third-generation semiconductors such as silicon carbide/gallium nitride, IGBT, power devices, power electronics and automotive semiconductors, etc. It will comprehensively showcase the latest manufacturing and solutions of integrated circuits and semiconductors.

SEMI-e has gone deep in the field of semiconductor exhibitions for many years and thus developed into one of the most influential professional exhibition platforms in the semiconductor industry. The 7th Shenzhen International Semiconductor Exhibition (SEMI-e 2025) is jointly organized by a number of industry associations and will cover an exhibition area of 60,000 m². With over 900 exhibitors, it will launch 50+ exciting theme activities and is expected to attract more than 70,000 industry visitors.

For SEMI-e 2024, its exhibition area was nearly 60,000 square meters, gathering 815 exhibitors. Its exhibits included semiconductor equipment, chip design/wafer manufacturing/advanced packaging, third-generation semiconductors, semiconductor components, advanced materials, automotive semiconductors and other fields, covering the entire semiconductor industry chain. At the same time, "The 6th Shenzhen Semiconductor Industry Technology Summit", "The 5th Third-Generation Semiconductor Industry Development Summit Technology Forum", "2024 China Automotive Semiconductor Conference", "2024 Summit for Current Semiconductor Localization Trend" and "Bao'an Business Environment Promotion and Semiconductor Enterprise Supply and Demand Matchmaking Conference" were held, which focused on such hot topics as automotive chips, autonomous driving technology, automotive power devices, advanced packaging and testing technologies and new semiconductor (GaN/SiC) material manufacturing. Such conferences also attracted experts and professionals from such fields as the semiconductor industry, automotive new energy and consumer electronics to visit and exchange ideas, promoted capacity expansion, and helped to deeply connect high-quality resources. In partnership with HLMC, HT-tech, Tongfu Microelectronics, ACM Research, Tankeblue, 45th Research Institute of China Electronics Technology Group Corporation, Zhonghuan Advanced, BYD Semiconductor, NCAP China, Nansha Wafer, Naura, Shanghai Microelectronic Equipment, Changchuan Technology, Lead Intelligent, Keyence, Semi-tech, FMIC, Global Power Technology, Shanghai Belling, SCY, ASTSiC, UNICOMP, Cfmee Microelectronics, Hualin Jiaye, Sunlord, Zhongke Saifei, Zhicheng Semiconductor, SZLQ Intelligence, Maxwell, Synlight Semiconductor, Tianyu, Liande Semiconductor, Yujing Machinery, SPARC, Xinxiang, DG Smart Win, Mind Vision, Global, Youngen, Ked Tech, Vatech, LiM, Kawasaki Robotics, Kinglai, MicroASM, Yujing Technology, INTO SEMI, Lebosemi, Shuocheng Group, Leica, Dynamikwell, Yuhuan, Shenwu, Autowell, PLANARY and other enterprises, SEMI-e concentrates on chips to seek development and makes every effort to create a high-quality industry event. SEMI-e is committed to providing exhibitors with a high-level, high-end and high-quality platform for exhibition and communication!

In addition, from the perspective of the entire industry chain, Shenzhen is undoubtedly one of the best markets for innovation and application in the semiconductor industry in Asia, attracting the attention of many well-known enterprises and investors. SEMI-e relies on the solid foundation laid in the early stage to provide precise market matching services for exhibitors. The visiting enterprises included Huawei, CanSemi, Sungrow, Yangtze Memory, SMIC, SHHIC, Zensemi, Intel, CR Microelectronics, San'an, FMIC, Huatian, PST, JCET, Tongfu Microelectronics, Pengxinwei, Hynix, Tankeblue, Naura, ACM Research, ROHM, Infineon, BYD, NIO Motors, FAW, Xiaopeng and other leading enterprises, covering wafer fabs, packaging and testing plants, equipment manufacturers, silicon carbide, automotive manufacturers, inverter factories, consumer electronics, power electronics, etc. from over 50 industries. In addition, the Guangdong Integrated Circuit Park was visited by 352 organizations including Bao'an District Bureau of Commerce, Bao'an District Enterprise Service Center, Institute of Semiconductors of Guangdong Academy of Sciences, Shenzhen Semiconductor Industry Association, Semiconductor Display Association, etc. SEMI-e is not only a showcase for technology, but also an important platform for industry exchange, cooperation and innovation. Through effective market exposure, precise business matching can be achieved!

From comprehensive promotion and advertising to meticulous on-site service, the 7th Shenzhen International Semiconductor Exhibition (SEMI-e 2025) is currently in full swing to attract exhibitors and buyers. We cordially invite our "old friends" to make a comeback, and also welcome more "new faces" to join us. We are looking forward to meet you at this influential and professional technology feast in the semiconductor industry!

Exhibition Scope



Exhibition area for Chip Design and Wafer Manufacturing

Integrated circuit design and chips, EDA, MCU, wafer manufacturing and equipment and components, etc

Exhibition area for Chiplet and Advanced Packaging

Chiplet, SiP packaging, wafer level packaging (WLP), 3D packaging, panel level packaging (PLP), TSV/TGV packaging, organic/silicon/glass substrates, packaging substrates, packaging carriers, IC carriers, semiconductor packaging materials and equipment, etc

Exhibition Area for Specialized Equipment/ Components for Semiconductors

Thinning machines, mono-crystal furnaces, grinding machines, heat treatment equipment, lithography machines, etching machines, ion implantation equipment, CVD/PVD equipment, cleaning equipment, cutting machines, mounting machine, bonding machines, testing machines, sorting machines, probe stations and components, etc.

Exhibition Area for Advanced Materials/Carbon Materials/Diamond Semiconductors

Silicon wafers and silicon-based materials, photomasks, electronic gases, photoresist and its supporting reagents, CMP polishing materials, target materials, packaging substrates, lead frames, bonding wires, ceramic substrates, chip bonding materials, carbonbased materials, diamond semiconductors, graphite materials, superhard materials, etc.

Cover the whole industry chain

Exhibition Area for Third-Generation Semiconductors

Gallium nitride (GaN) and silicon carbide (SiC), zinc oxide (ZnO), diamond, wafers, substrates and epitaxy, power devices, IGBT packaging materials, RF devices and processing equipment, etc.

Exhibition Scope

Exhibition Area for Components

Passive components, semiconductor discrete devices/IGBT, 5G core components, special electronics, components, power management, sensors, memories, connector relays, cables, plug-in devices, crystal oscillators, resistors, display devices, diodes, transistor filtering components, switches, and component materials and equipment, etc.

Cover the whole industry chain

Exhibition Area for Power Devices/Power Electronics/ Automotive Semiconductors

Automotive grade semiconductor control/computing chips, power semiconductors (IGBT and MOSFET), automotive grade SiC modules, power management chips, automotive electronic micro assembly and power devices, packaging and testing equipment, automation equipment, etc.

Exhibition Area for Computing Power, Storage, Artificial Intelligence, and CPO Packaging

Artificial intelligence chips, solutions, computing power chips and solutions, algorithm solutions, data storage, optoelectronic co-packaging modules and technologies and equipment, etc.

Exhibition Area for Semiconductor Display/ Mini/Micro LED

OLED, AMOLED, Mini/Micro LED displays, flexible displays, materials and devices, etc.

Exhibition area for international brands

International semiconductor material suppliers, well-known equipment suppliers, well-known packaging, testing and manufacturing enterprises, OEM manufacturers, etc.



Buyer Analysis



Factory affairs Production/processing Quality management (QE/SQE/QA/QC) Sales Marketing management Visitor Position

Others

General manager/chairman/CEO

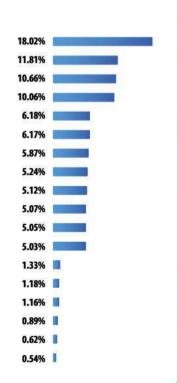
Product development

Procurement

21.76% 16.42% 16.29% 14.12% 12.51% 6.28%



Chip design/wafer manufacturing/packaging Semiconductor equipment/components Third-generation semiconductors New energy vehicles/rail transit Semiconductor materials Computing power/storage/artificial intelligence Inverters/charging/photovoltaic Electricity/electrical/electronics Industrial manufacturing/mechanical equipment Inverters/charging/photovoltaic/energy storage IC carrier boards/ceramic substrates Home appliances/consumer electronics/medical equipment Semiconductor related research institutes and industrial parks Machine vision/digital products Lighting/display industrial control Optical communication/information processing/optoelectronics Internet of Things/security Other



Previous Buyers (to name but a few)

Wafer Fabrication

Samsung Xi'an/Intel
Dalian/SMIC/SK Hynix
Semiconductor/TSMC Nanjing/
CR Microelectronics/TSMC/
United Semi/Hejian/Yangtze
Memory/Jinghe Integrated/
Yandong Microelectronics/
GTA Semiconductor/Changxin
Memory/FMIC/HHGrace/
Tianjin Zhonghuan/Silan
Microelectronics/CanSemi/MS/
TowerJazz/Lijing Technology/DB
Hitek/UMC/PSMC/SMEC/FMIC/
Pengxinwei/SwaySure/PST

Design/ Chips/ Components

Nvidia/HiSilicon Semiconductor/ 7TF Microelectronics/ STMicroelectronics/NXP Semiconductors/SMiT/HDSC/ FMIC/GOODiX/Infineon/Shanghai Belling/Silan Microelectronics/ Macronix/GZLG/Mind Motion/ GigaDevice/Cmsemicon/Hangshun Technology/AllwinnerTechnology/ Murata/SK Hynix/ROHM Semiconductor/Yangtze Memory/ Empyrean/BYD Microelectronics/ Horizon Robotics/SCY/ON Semiconductor/Black Sesame/ Cambrian/SemiDrive/Nations/ Longsys/WINSEMI

Packaging and Testing Enterprises

JCET/HT Tech/Tongfu Microelectronics/ASE Group/ NXP/San'an/HHGrace/HT Tech/ Xinchao Technology/Hongkai Technology/CR Microelectronics/ Amkor Technology/Jiangsu JJ Microelectronics/NCAP China/ Chippacking/Tatfook/Kimtigo Semiconductor/Hottech/ Cosmos Wealth Technologies/ FM Electronics/Carsem Semiconductor/GOOD-ARK/CTK/ GTBF/Fozhixin Microelectronics/ Fenghua Semiconductor/Blue Rocket Electronics/Forehope Electronic/JSSI Semiconductor

SiC/IGBT Wafers/Discrete Devices

CR Microelectronics/Infineon/
Silan Microelectronics/Nexperia/
Accopower/ON Semiconductor/
BYD/Hebei Synlight/Changsha
San'an/Shanxi SEMISiC/
CRRC Times/Starpower
Semiconductor/Changfei
Advanced/AccoPower/Nansha
Wafer/Yangjie Technology/
STMicroelectronics/ GRECON
Semi/Tankeblue/Wingtech/
SICC/Jingdao Microelectronics/
SCC



Tesla/BYD/NIO Motors/Xiaopeng Motors/Xiaomi Motors/BAIC New Energy/Great Wall Motors/SAIC Roewe/FAW/Zhongtong Bus/ Chery Automobile/SAIC Group/ Jianghuai Automobile/Jiangling Motors/Ideal Automobile/ Aion New Energy/Leapmotor/ Foton Ouhui/Geely Automobile/ Zhongcheng Industrial

Equipment Enterprises

Naura/Shanghai Microelectronic Equipment/Institute of Optics and Electronics, Chinese Academy of Sciences/Yitang Semiconductor/ Cmsemicon/45th Research Institute of China Electronics Technology Group Corporation/ Huaxing Yuanchuang/ Secote/Jiejia Weichuang/PNC Technology/ACM Research/ Piotech/Zhenxin Semiconductor/ Skyverse/TDG-MT/Jingce Electronic/Kingsemi/Shanghai Sinyang/Jingyi Automation/ Hwatsing/CFMEE/Changchuan Technology/Han's Laser/ Jingsheng Electromechanical/ S-KING/SRI Intellectual/Hexagon

Previous Exhibitors



Previous Exhibitors



Guests from Previous Summits

The Sixth Shenzhen Semiconductor Industry Technology Summit



Zhou Xuchao Deputy General Manager of Automatic Optical Inspection Division, Shanghai Microelectronics



Yao Ting Sales Manager, Shengmei Semiconductor



Mei Shuang General Manager Wuhan Luobo Semiconductor



Yin Chengke Founder & Chairman, Super Intelligent Technology



Zhang Chunyan R&D Director, Huajin Semicanductar



Wang Ruiji Director of Software Development Center, Huaxin Intelligent



Fang Haoquan Vice General Manager of Advanced Manufacturing Division, Megarobo Technology



Liu Ju Engineer, Suzhou Suxin nental Technology



Ali Imran Director of R&D Center, Manufacturing Industry Innovation Center Co., Ltd.



Wang Changqing Senior Consultant in the Semiconductor Industry, Dinghua Intelligent

2024 China Automotive Semiconductor Conference



Cao Changfeng Chief Engineer, Great Wall Automobile



Sun Jiazhao Automotive industry Solution Expert, Huawei



Liu Renlong Hardware Development and Product Platform Manager, Dongfeng Motor Corporation R&D Institute



Zhou Hu Associate Professor, Geely University of China



Liao Lei Chief Engineer of Automotive Software and R&D Center Expert, GAC R&D Center



Zou Guangcai Deputy General Manager,

National New Energy Vehicle Technology Innovation Center Deputy Secretary General, China Automotive Chip Industry Innovation Strategic Alliance



Xia Xianzhao

Deputy Secretary General, China Automotive Chip Standard Testing and Certification Alliance



Tang Zhenning Marketing Director, Shanghai Belling



Chen Bohan

Director of Optical Technology Research and Development Department, San'an Optical Communication



Zhou Xiaoyang

CEO, Xinjuneng Semiconductor

Guests from Previous Summits

The 5th Third-Generation Semiconductor Industry Development Summit Technology Forum



Guo Yu Technical Director, Tankeblue



Lu Chunxue
Vice General Manager of the
Development Department of
Compound Semiconductor
Industry, NAURA



Xie Wenbin Senior Chief Engineer of Product Application, Innoscience



Zhou Zhenhong CEO, BelGaN, a Belgian wafer OEM factory



Zhang Dajiang R&D Director, Zhuhai Gallium Future



Lin Liteng General Manager, Shaanxi Yuteng Electronic



Wang Shouzhi General Manager, Shandong Jingjia Semiconductor



Liang Hu General Manager/CTO/Chief Scientist, Fuzhou Gallium Valley



Zhang Zefang Chairman, PLANARY



Ma Kangfu Assistant General Manager, Semicore Crystal



Duan ShuguoDeputy General Manager, Keyou
Semiconductor



Guan Chunyang
Director and President, Jiangsu
Jixin Advanced Materials



Fang Ziwen
General Manager, AIXTRON



Zhang Yongqiang
Product Director, Pusing
Electronic Technology



Chen Yuzhong
CEO, Dalian Chuangrui Spectral
Technology



Xiao Kaixiang Marketing Manager, Nawei Semiconductor



Cai Xiongfei
Vice General Manager, Shenzhen
BASiC Semiconductor Ltd.



Yu Yapeng Industry Solution Manager, Qingdao Gaoce Technology Co., Ltd.



Song Wenchao
Deputy Director of Semiconductor
Cleaning Equipment Division, 45th
Research Institute of China Electronics
Technology Group Corporation



Cai Changyi Senior Director of R&D Laboratory, Beijing Jingyi Jingwei Technology



Wang Lezhi Co-founder, Guangdong Zhineng Technology



Mei Lingliang
General Managet, Dongguan
Keshite Technology



Liu Ran

Application Technology Director,
Shenzhen Zhongii New Materials



Li Xueguang

Marketing Director, Jinghang
Special Carbon Technology



Li Jinghui

Marketing Manager, Guangzhou

Yuesheng Semiconductor

Fruitment

Previous Review

60,000m²

Exhibition Area





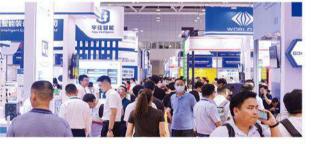
815 Exhibitors



79,586

Visitors







51'

Speakers

25% Visitor increase



100⁺
Media Partners

50⁺
Concurrent Activities



2,165⁺

Attendees

Media Promotion









Media Partners



Exhibition Highlights

Concentrate on "Chips" to seek development

As a highly influential and professional semiconductor exhibition in the industry, SEMI-e will gather over 900 exhibitors, focusing on artificial intelligence, computing power storage, chip design, wafer manufacturing, advanced packaging, specialized equipment and components for semiconductors, advanced materials and carbon materials, third-generation semiconductors such as silicon carbide/gallium nitride, IGBT, power devices, power electronics and automotive semiconductors, etc. It will comprehensively showcase the latest manufacturing and solutions of integrated circuits and semiconductors, with an exhibition area of 60000 m2 and is expected to attract over 70,000 industry visitors.

The concurrent summits focus on market hotspots

Relying on the SEMI-e exhibition, more than 50 theme forums will be held concurrently to discuss and exchange new trends in the development of the semiconductor industry. At that time, authoritative experts, outstanding entrepreneurs, and industry elites from the semiconductor field will gather to discuss and share the semiconductor industry pattern, cutting-edge technologies, and market trends on site, and jointly unlock the path to cost reduction, efficiency improvement, and high-quality development of the semiconductor industry chain, achieving the linkage of "exhibition" and "forums". SEMI-e is committed to providing exhibitors with a high-level, high-end and high-quality platform for exhibition and communication!

Integrate resources to achieve business matching

SEMI-e has integrated years of industry resources, and has a powerful resource database, providing one-stop solutions for resource exchange, information exchange, and product trade needs. Facing the increasing market demand, SEMI-e has gathered many well-known companies in the industry, providing exhibitors with huge market opportunities. Through effective market exposure, exhibitors can have broader exposure to target customers and achieve precise business matching!

A comprehensive media matrix for one-stop promotion

SEMI-e focuses on promoting and shaping exhibitors, collaborating with over 100 media partners to create a comprehensive media matrix. It provides one-stop promotional services through advertising placement, private streaming, on-site interviews and live streaming. In order to fully ensure the popularity and effectiveness of the exhibition, the sponsor has placed a large number of advertisements online and offline, which are not only redirected to mini programs, official accounts and video accounts, but also have a large coverage of the Internet, accurately radiate professional buyers, continue to expand publicity efforts, fully integrate industry resources, and further consolidate the publicity work for buyers, so as to maximize exhibitors' participation benefits, and build a high-quality event!



Exhibition Notice





Domestic exhibitors

Standard booth: CNY 25,800/booth (3×3 m²)
Raw space: CNY 2,580/m² (at least 36 m²)

Overseas exhibitors

Standard booth: USD 4,500/booth (3×3 m²) Raw space: USD 450/ m² (at least 36 m²)







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A highly influential and professional semiconductor exhibition in the industry

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WeChat Mini Program



WeChat Official Account

Inquiry about Participation

Miss Wang: +86 189 2679 9965 Miss Jia: +86 135 4326 6785

www.semi-e.com